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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	317000
Number of Logic Elements/Cells	840000
Total RAM Bits	53248000
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-HBGA (45x45)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5see9h40i3l">https://www.e-xfl.com/product-detail/intel/5see9h40i3l</a>

**Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering <sup>(1), (2), (3)</sup> (Part 2 of 2)**

Transceiver Speed Grade	Core Speed Grade							
	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L	I3YY	I4
3 GX channel—8.5 Gbps	—	Yes	Yes	Yes	—	Yes	Yes <sup>(4)</sup>	Yes

**Notes to Table 1:**

- (1) C = Commercial temperature grade; I = Industrial temperature grade.  
 (2) Lower number refers to faster speed grade.  
 (3) C2L, I2L, and I3L speed grades are for low-power devices.  
 (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

**Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering <sup>(1), (2)</sup>**

Transceiver Speed Grade	Core Speed Grade			
	C1	C2	I2	I3
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	—	—
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes

**Notes to Table 2:**

- (1) C = Commercial temperature grade; I = Industrial temperature grade.  
 (2) Lower number refers to faster speed grade.

**Absolute Maximum Ratings**

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

**Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)**

Symbol	Description	Minimum	Maximum	Unit
V <sub>CC</sub>	Power supply for core voltage and periphery circuitry	−0.5	1.35	V
V <sub>CCPT</sub>	Power supply for programmable power technology	−0.5	1.8	V
V <sub>CCPGM</sub>	Power supply for configuration pins	−0.5	3.9	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	−0.5	3.4	V
V <sub>CCBAT</sub>	Battery back-up power supply for design security volatile key register	−0.5	3.9	V
V <sub>CCPD</sub>	I/O pre-driver power supply	−0.5	3.9	V
V <sub>CCIO</sub>	I/O power supply	−0.5	3.9	V

**Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)**

Symbol	Description	Minimum	Maximum	Unit
V <sub>CCD_FPLL</sub>	PLL digital power supply	−0.5	1.8	V
V <sub>CCA_FPLL</sub>	PLL analog power supply	−0.5	3.4	V
V <sub>I</sub>	DC input voltage	−0.5	3.8	V
T <sub>J</sub>	Operating junction temperature	−55	125	°C
T <sub>STG</sub>	Storage temperature (No bias)	−65	150	°C
I <sub>OUT</sub>	DC output current per pin	−25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

**Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices**

Symbol	Description	Devices	Minimum	Maximum	Unit
V <sub>CCA_GXBL</sub>	Transceiver channel PLL power supply (left side)	GX, GS, GT	−0.5	3.75	V
V <sub>CCA_GXBR</sub>	Transceiver channel PLL power supply (right side)	GX, GS	−0.5	3.75	V
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	−0.5	3.75	V
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCHIP_R</sub>	Transceiver hard IP power supply (right side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCHSSI_R</sub>	Transceiver PCS power supply (right side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCR_GXBL</sub>	Receiver analog power supply (left side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	−0.5	1.35	V
V <sub>CCT_GXBL</sub>	Transmitter analog power supply (left side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCT_GXBR</sub>	Transmitter analog power supply (right side)	GX, GS, GT	−0.5	1.35	V
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	−0.5	1.35	V
V <sub>CCL_GTBR</sub>	Transmitter clock network power supply (right side)	GT	−0.5	1.35	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	−0.5	1.8	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	−0.5	1.8	V

#### Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to −2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

**Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)**

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
$V_{CCR\_GXBR}$ (2)	Receiver analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCR\_GTBR}$	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
$V_{CCT\_GXBL}$ (2)	Transmitter analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCT\_GXBR}$ (2)	Transmitter analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCT\_GTBR}$	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
$V_{CCL\_GTBR}$	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
$V_{CCH\_GXBL}$	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
$V_{CCH\_GXBR}$	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

**Notes to Table 7:**

- (1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.
- (2) Refer to Table 8 to select the correct power supply level for your design.
- (3) When using ATX PLLs, the supply must be 3.0 V.
- (4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

### I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

**Table 9. I/O Pin Leakage Current for Stratix V Devices <sup>(1)</sup>**

Symbol	Description	Conditions	Min	Typ	Max	Unit
$I_I$	Input pin	$V_I = 0 \text{ V to } V_{CCIO\text{MAX}}$	-30	—	30	$\mu\text{A}$
$I_{OZ}$	Tri-stated I/O pin	$V_O = 0 \text{ V to } V_{CCIO\text{MAX}}$	-30	—	30	$\mu\text{A}$

**Note to Table 9:**

(1) If  $V_O = V_{CCIO}$  to  $V_{CCIO\text{MAX}}$ , 100  $\mu\text{A}$  of leakage current per I/O is expected.

### Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

**Table 10. Bus Hold Parameters for Stratix V Devices**

Parameter	Symbol	Conditions	V <sub>CCIO</sub>										Unit
			1.2 V		1.5 V		1.8 V		2.5 V		3.0 V		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I <sub>SUSL</sub>	V <sub>IN</sub> > V <sub>IL</sub> (maximum)	22.5	—	25.0	—	30.0	—	50.0	—	70.0	—	μA
High sustaining current	I <sub>SUSH</sub>	V <sub>IN</sub> < V <sub>IH</sub> (minimum)	−22.5	—	−25.0	—	−30.0	—	−50.0	—	−70.0	—	μA
Low overdrive current	I <sub>ODL</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	120	—	160	—	200	—	300	—	500	μA
High overdrive current	I <sub>ODH</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	−120	—	−160	—	−200	—	−300	—	−500	μA
Bus-hold trip point	V <sub>TRIP</sub>	—	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

### On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

**Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices <sup>(1)</sup> (Part 1 of 2)**

Symbol	Description	Conditions	Calibration Accuracy				Unit
			C1	C2,I2	C3,I3, I3YY	C4,I4	
25- $\Omega$ $R_S$	Internal series termination with calibration (25- $\Omega$ setting)	$V_{\text{CCIO}} = 3.0, 2.5, 1.8, 1.5, 1.2 \text{ V}$	$\pm 15$	$\pm 15$	$\pm 15$	$\pm 15$	%

**Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 2 of 2)**

Symbol	Description	Conditions	Resistance Tolerance				Unit
			C1	C2, I2	C3, I3, I3YY	C4, I4	
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 1.8 and 1.5 V	±30	±30	±40	±40	%
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 1.2 V	±35	±35	±50	±50	%
100-Ω R <sub>D</sub>	Internal differential termination (100-Ω setting)	V <sub>CCPD</sub> = 2.5 V	±25	±25	±25	±25	%

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

**Equation 1. OCT Variation Without Recalibration for Stratix V Devices <sup>(1), (2), (3), (4), (5), (6)</sup>**

$$R_{OCT} = R_{SCAL} \left( 1 + \left\langle \frac{dR}{dT} \times \Delta T \right\rangle \pm \left\langle \frac{dR}{dV} \times \Delta V \right\rangle \right)$$

**Notes to Equation 1:**

- (1) The R<sub>OCT</sub> value shows the range of OCT resistance with the variation of temperature and V<sub>CCIO</sub>.
- (2) R<sub>SCAL</sub> is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power-up.
- (4) ΔV is the variation of voltage with respect to the V<sub>CCIO</sub> at power-up.
- (5) dR/dT is the percentage change of R<sub>SCAL</sub> with temperature.
- (6) dR/dV is the percentage change of R<sub>SCAL</sub> with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

**Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 1 of 2) <sup>(1)</sup>**

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
dR/dV	OCT variation with voltage without recalibration	3.0	0.0297	% / mV
		2.5	0.0344	
		1.8	0.0499	
		1.5	0.0744	
		1.2	0.1241	

## Internal Weak Pull-Up Resistor

Table 16 lists the weak pull-up resistor values for Stratix V devices.

**Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices <sup>(1), (2)</sup>**

Symbol	Description	V <sub>CCIO</sub> Conditions (V) <sup>(3)</sup>	Value <sup>(4)</sup>	Unit
R <sub>PU</sub>	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option.	3.0 ±5%	25	kΩ
		2.5 ±5%	25	kΩ
		1.8 ±5%	25	kΩ
		1.5 ±5%	25	kΩ
		1.35 ±5%	25	kΩ
		1.25 ±5%	25	kΩ
		1.2 ±5%	25	kΩ

### Notes to Table 16:

- (1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ.
- (3) The pin pull-up resistance values may be lower if an external source drives the pin higher than V<sub>CCIO</sub>.
- (4) These specifications are valid with a ±10% tolerance to cover changes over PVT.

## I/O Standard Specifications

Table 17 through Table 22 list the input voltage (V<sub>IH</sub> and V<sub>IL</sub>), output voltage (V<sub>OH</sub> and V<sub>OL</sub>), and current drive characteristics (I<sub>OH</sub> and I<sub>OL</sub>) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The V<sub>OL</sub> and V<sub>OH</sub> values are valid at the corresponding I<sub>OH</sub> and I<sub>OL</sub>, respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to “Glossary” on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012\_486.

**Table 17. Single-Ended I/O Standards for Stratix V Devices**

I/O Standard	V <sub>CCIO</sub> (V)			V <sub>IL</sub> (V)		V <sub>IH</sub> (V)		V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I <sub>OL</sub> (mA)	I <sub>OH</sub> (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
LVTTTL	2.85	3	3.15	−0.3	0.8	1.7	3.6	0.4	2.4	2	−2
LVC MOS	2.85	3	3.15	−0.3	0.8	1.7	3.6	0.2	V <sub>CCIO</sub> − 0.2	0.1	−0.1
2.5 V	2.375	2.5	2.625	−0.3	0.7	1.7	3.6	0.4	2	1	−1
1.8 V	1.71	1.8	1.89	−0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.45	V <sub>CCIO</sub> − 0.45	2	−2
1.5 V	1.425	1.5	1.575	−0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 * V <sub>CCIO</sub>	0.75 * V <sub>CCIO</sub>	2	−2
1.2 V	1.14	1.2	1.26	−0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 * V <sub>CCIO</sub>	0.75 * V <sub>CCIO</sub>	2	−2

**Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Devices**

I/O Standard	$V_{CCIO}$ (V)			$V_{REF}$ (V)			$V_{TT}$ (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	$V_{REF} - 0.04$	$V_{REF}$	$V_{REF} + 0.04$
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	$V_{REF} - 0.04$	$V_{REF}$	$V_{REF} + 0.04$
SSTL-15 Class I, II	1.425	1.5	1.575	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$
SSTL-135 Class I, II	1.283	1.35	1.418	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$
SSTL-125 Class I, II	1.19	1.25	1.26	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$
SSTL-12 Class I, II	1.14	1.20	1.26	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.53 * V_{CCIO}$	—	$V_{CCIO}/2$	—
HSUL-12	1.14	1.2	1.3	$0.49 * V_{CCIO}$	$0.5 * V_{CCIO}$	$0.51 * V_{CCIO}$	—	—	—

**Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 1 of 2)**

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	$V_{OL}$ (V)	$V_{OH}$ (V)	$I_{OI}$ (mA)	$I_{OH}$ (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.608$	$V_{TT} + 0.608$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.81$	$V_{TT} + 0.81$	16.2	-16.2
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.603$	$V_{TT} + 0.603$	6.7	-6.7
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	8	-8
SSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	16	-16
SSTL-135 Class I, II	—	$V_{REF} - 0.09$	$V_{REF} + 0.09$	—	$V_{REF} - 0.16$	$V_{REF} + 0.16$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
SSTL-125 Class I, II	—	$V_{REF} - 0.85$	$V_{REF} + 0.85$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
SSTL-12 Class I, II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—



**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 2 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Spread-spectrum downspread	PCIe	—	0 to -0.5	—	—	0 to -0.5	—	—	0 to -0.5	—	%
On-chip termination resistors <sup>(21)</sup>	—	—	100	—	—	100	—	—	100	—	$\Omega$
Absolute $V_{MAX}$ <sup>(5)</sup>	Dedicated reference clock pin	—	—	1.6	—	—	1.6	—	—	1.6	V
	RX reference clock pin	—	—	1.2	—	—	1.2	—	—	1.2	
Absolute $V_{MIN}$	—	-0.4	—	—	-0.4	—	—	-0.4	—	—	V
Peak-to-peak differential input voltage	—	200	—	1600	200	—	1600	200	—	1600	mV
$V_{ICM}$ (AC coupled) <sup>(3)</sup>	Dedicated reference clock pin	1050/1000/900/850 <sup>(2)</sup>			1050/1000/900/850 <sup>(2)</sup>			1050/1000/900/850 <sup>(2)</sup>			mV
	RX reference clock pin	1.0/0.9/0.85 <sup>(4)</sup>			1.0/0.9/0.85 <sup>(4)</sup>			1.0/0.9/0.85 <sup>(4)</sup>			V
$V_{ICM}$ (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	250	—	550	mV
Transmitter REFCLK Phase Noise (622 MHz) <sup>(20)</sup>	100 Hz	—	—	-70	—	—	-70	—	—	-70	dBc/Hz
	1 kHz	—	—	-90	—	—	-90	—	—	-90	dBc/Hz
	10 kHz	—	—	-100	—	—	-100	—	—	-100	dBc/Hz
	100 kHz	—	—	-110	—	—	-110	—	—	-110	dBc/Hz
	$\geq 1$ MHz	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) <sup>(17)</sup>	10 kHz to 1.5 MHz (PCIe)	—	—	3	—	—	3	—	—	3	ps (rms)
$R_{REF}$ <sup>(19)</sup>	—	—	1800 $\pm 1\%$	—	—	1800 $\pm 1\%$	—	—	1800 $\pm 1\%$	—	$\Omega$
<b>Transceiver Clocks</b>											
fixedclk clock frequency	PCIe Receiver Detect	—	100 or 125	—	—	100 or 125	—	—	100 or 125	—	MHz

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 6 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode	—	—	500	—	—	500	—	—	500	ps
<b>CMU PLL</b>											
Supported Data Range	—	600	—	12500	600	—	12500	600	—	8500/ 10312.5 (24)	Mbps
t <sub>pll_powerdown</sub> <sup>(15)</sup>	—	1	—	—	1	—	—	1	—	—	μs
t <sub>pll_lock</sub> <sup>(16)</sup>	—	—	—	10	—	—	10	—	—	10	μs
<b>ATX PLL</b>											
Supported Data Rate Range	VCO post-divider L=2	8000	—	14100	8000	—	12500	8000	—	8500/ 10312.5 (24)	Mbps
	L=4	4000	—	7050	4000	—	6600	4000	—	6600	Mbps
	L=8	2000	—	3525	2000	—	3300	2000	—	3300	Mbps
	L=8, Local/Central Clock Divider =2	1000	—	1762.5	1000	—	1762.5	1000	—	1762.5	Mbps
t <sub>pll_powerdown</sub> <sup>(15)</sup>	—	1	—	—	1	—	—	1	—	—	μs
t <sub>pll_lock</sub> <sup>(16)</sup>	—	—	—	10	—	—	10	—	—	10	μs
<b>fPLL</b>											
Supported Data Range	—	600	—	3250/ 3125 <sup>(25)</sup>	600	—	3250/ 3125 <sup>(25)</sup>	600	—	3250/ 3125 <sup>(25)</sup>	Mbps
t <sub>pll_powerdown</sub> <sup>(15)</sup>	—	1	—	—	1	—	—	1	—	—	μs

Table 24 shows the maximum transmitter data rate for the clock network.

**Table 24. Clock Network Maximum Data Rate Transmitter Specifications <sup>(1)</sup>**

Clock Network	ATX PLL			CMU PLL <sup>(2)</sup>			fPLL		
	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 <sup>(3)</sup>	14.1	—	6	12.5	—	6	3.125	—	3
x6 <sup>(3)</sup>	—	14.1	6	—	12.5	6	—	3.125	6
x6 PLL Feedback <sup>(4)</sup>	—	14.1	Side-wide	—	12.5	Side-wide	—	—	—
xN (PCIe)	—	8.0	8	—	5.0	8	—	—	—
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above and below PLL	3.125	3.125	Up to 13 channels above and below PLL
	—	8.01 to 9.8304	Up to 7 channels above and below PLL						

**Notes to Table 24:**

- (1) Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.
- (2) ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.
- (3) Channel span is within a transceiver bank.
- (4) Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

Table 27 shows the  $V_{OD}$  settings for the GX channel.

**Table 27. Typical  $V_{OD}$  Setting for GX Channel, TX Termination = 100  $\Omega$  <sup>(2)</sup>**

Symbol	$V_{OD}$ Setting	$V_{OD}$ Value (mV)	$V_{OD}$ Setting	$V_{OD}$ Value (mV)
<b><math>V_{OD}</math> differential peak to peak typical <sup>(3)</sup></b>	0 <sup>(1)</sup>	0	32	640
	1 <sup>(1)</sup>	20	33	660
	2 <sup>(1)</sup>	40	34	680
	3 <sup>(1)</sup>	60	35	700
	4 <sup>(1)</sup>	80	36	720
	5 <sup>(1)</sup>	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
	15	300	47	940
	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

**Note to Table 27:**

- (1) If TX termination resistance = 100 $\Omega$ , this VOD setting is illegal.
- (2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.
- (3) Refer to Figure 2.

**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5) <sup>(1)</sup>**

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Transmitter REFCLK Phase Noise (622 MHz) <sup>(18)</sup>	100 Hz	—	—	-70	—	—	-70	dBc/Hz
	1 kHz	—	—	-90	—	—	-90	
	10 kHz	—	—	-100	—	—	-100	
	100 kHz	—	—	-110	—	—	-110	
	≥ 1 MHz	—	—	-120	—	—	-120	
Transmitter REFCLK Phase Jitter (100 MHz) <sup>(15)</sup>	10 kHz to 1.5 MHz (PCIe)	—	—	3	—	—	3	ps (rms)
RREF <sup>(17)</sup>	—	—	1800 ± 1%	—	—	1800 ± 1%	—	Ω
<b>Transceiver Clocks</b>								
fixedclk clock frequency	PCIe Receiver Detect	—	100 or 125	—	—	100 or 125	—	MHz
Reconfiguration clock (mgmt_clk_clk) frequency	—	100	—	125	100	—	125	MHz
<b>Receiver</b>								
Supported I/O Standards	—	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS						
Data rate (Standard PCS) <sup>(21)</sup>	GX channels	600	—	8500	600	—	8500	Mbps
Data rate (10G PCS) <sup>(21)</sup>	GX channels	600	—	12,500	600	—	12,500	Mbps
Data rate	GT channels	19,600	—	28,050	19,600	—	25,780	Mbps
Absolute V <sub>MAX</sub> for a receiver pin <sup>(3)</sup>	GT channels	—	—	1.2	—	—	1.2	V
Absolute V <sub>MIN</sub> for a receiver pin	GT channels	-0.4	—	—	-0.4	—	—	V
Maximum peak-to-peak differential input voltage V <sub>ID</sub> (diff p-p) before device configuration <sup>(20)</sup>	GT channels	—	—	1.6	—	—	1.6	V
	GX channels	<sup>(8)</sup>						
Maximum peak-to-peak differential input voltage V <sub>ID</sub> (diff p-p) after device configuration <sup>(16)</sup> , <sup>(20)</sup>	GT channels V <sub>CCR_GTB</sub> = 1.05 V (V <sub>ICM</sub> = 0.65 V)	—	—	2.2	—	—	2.2	V
	GX channels	<sup>(8)</sup>						
Minimum differential eye opening at receiver serial input pins <sup>(4)</sup> , <sup>(20)</sup>	GT channels	200	—	—	200	—	—	mV
	GX channels	<sup>(8)</sup>						

Figure 4 shows the differential transmitter output waveform.

**Figure 4. Differential Transmitter/Receiver Output/Input Waveform**

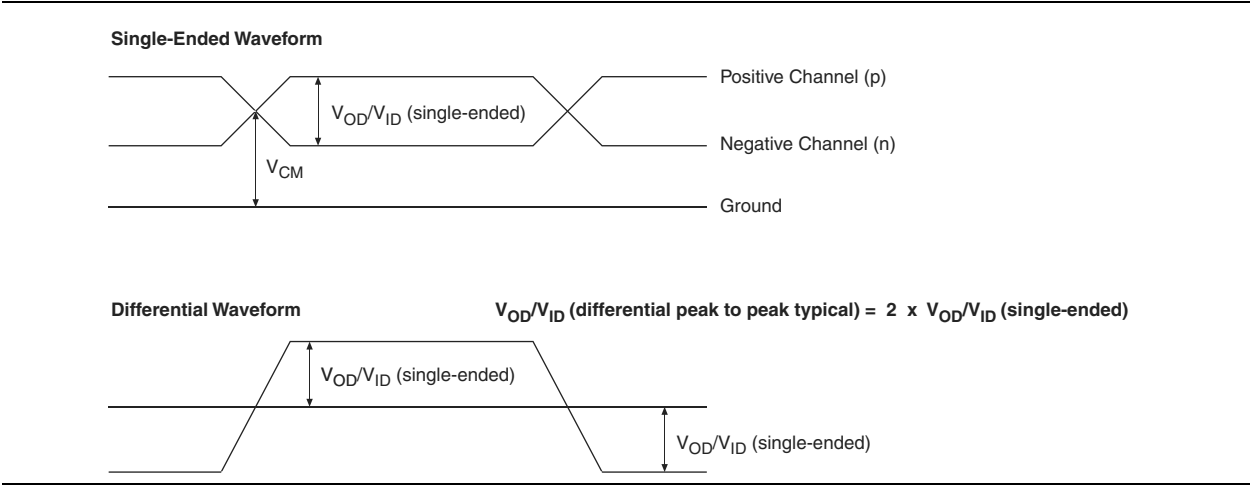


Figure 5 shows the Stratix V AC gain curves for GT channels.

**Figure 5. AC Gain Curves for GT Channels**

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

## Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

### Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

**Table 30. Clock Tree Performance for Stratix V Devices <sup>(1)</sup>**

Symbol	Performance			Unit
	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	
Global and Regional Clock	717	650	580	MHz
Periphery Clock	550	500	500	MHz

**Note to Table 30:**

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

**Table 36. High-Speed I/O Specifications for Stratix V Devices <sup>(1), (2)</sup> (Part 4 of 4)**

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f <sub>HSDR</sub> (data rate)	SERDES factor J = 3 to 10	(6)	—	(8)	(6)	—	(8)	(6)	—	(8)	(6)	—	(8)	Mbps
	SERDES factor J = 2, uses DDR Registers	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
<b>DPA Mode</b>														
DPA run length	—	—	—	1000 0	—	—	1000 0	—	—	1000 0	—	—	1000 0	UI
<b>Soft CDR mode</b>														
Soft-CDR PPM tolerance	—	—	—	300	—	—	300	—	—	300	—	—	300	± PPM
<b>Non DPA Mode</b>														
Sampling Window	—	—	—	300	—	—	300	—	—	300	—	—	300	ps

**Notes to Table 36:**

- (1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) This only applies to DPA and soft-CDR modes.
- (4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
- (5) This is achieved by using the **LVDS** clock network.
- (6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (f<sub>OUT</sub>) provided you can close the design timing and the signal integrity simulation is clean.
- (8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
- (9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (11) The F<sub>MAX</sub> specification is based on the fast clock used for serial data. The interface F<sub>MAX</sub> is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.
- (12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.
- (13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.
- (14) Requires package skew compensation with PCB trace length.
- (15) Do not mix single-ended I/O buffer within LVDS I/O bank.
- (16) Chip-to-chip communication only with a maximum load of 5 pF.
- (17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.



**Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)**

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

**Notes to Table 40:**

- (1) The typical value equals the average of the minimum and maximum values.
- (2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a –2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is  $[625 \text{ ps} + (10 \times 10 \text{ ps}) \pm 20 \text{ ps}] = 725 \text{ ps} \pm 20 \text{ ps}$ .

Table 41 lists the DQS phase shift error for Stratix V devices.

**Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock ( $t_{\text{DQS\_PSERR}}$ ) for Stratix V Devices <sup>(1)</sup>**

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

**Notes to Table 41:**

- (1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a –2 speed grade is  $\pm 78 \text{ ps}$  or  $\pm 39 \text{ ps}$ .

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

**Table 42. Memory Output Clock Jitter Specification for Stratix V Devices <sup>(1), (Part 1 of 2)</sup> <sup>(2), (3)</sup>**

Clock Network	Parameter	Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
Regional	Clock period jitter	$t_{\text{JIT(per)}}$	–50	50	–50	50	–55	55	–55	55	ps
	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	–100	100	–100	100	–110	110	–110	110	ps
	Duty cycle jitter	$t_{\text{JIT(duty)}}$	–50	50	–50	50	–82.5	82.5	–82.5	82.5	ps
Global	Clock period jitter	$t_{\text{JIT(per)}}$	–75	75	–75	75	–82.5	82.5	–82.5	82.5	ps
	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	–150	150	–150	150	–165	165	–165	165	ps
	Duty cycle jitter	$t_{\text{JIT(duty)}}$	–75	75	–75	75	–90	90	–90	90	ps

**Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)****Notes to Figure 13:**

- (1) Use this timing waveform and parameters when the DCLK-to-DATA[] ratio is >1. To find out the DCLK-to-DATA[] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF\_DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA[31..0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [ ] ratio is more than 1.

**Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[ ] Ratio is >1 <sup>(1)</sup>**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CF2CD}$	nCONFIG low to CONF_DONE low	—	600	ns
$t_{CF2ST0}$	nCONFIG low to nSTATUS low	—	600	ns
$t_{CFG}$	nCONFIG low pulse width	2	—	$\mu$ s
$t_{STATUS}$	nSTATUS low pulse width	268	1,506 <sup>(2)</sup>	$\mu$ s
$t_{CF2ST1}$	nCONFIG high to nSTATUS high	—	1,506 <sup>(2)</sup>	$\mu$ s
$t_{CF2CK}$ <sup>(5)</sup>	nCONFIG high to first rising edge on DCLK	1,506	—	$\mu$ s
$t_{ST2CK}$ <sup>(5)</sup>	nSTATUS high to first rising edge of DCLK	2	—	$\mu$ s
$t_{DSU}$	DATA [ ] setup time before rising edge on DCLK	5.5	—	ns
$t_{DH}$	DATA [ ] hold time after rising edge on DCLK	$N-1/f_{DCLK}$ <sup>(5)</sup>	—	s
$t_{CH}$	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CL}$	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CLK}$	DCLK period	$1/f_{MAX}$	—	s
$f_{MAX}$	DCLK frequency (FPP $\times 8/\times 16$ )	—	125	MHz
	DCLK frequency (FPP $\times 32$ )	—	100	MHz
$t_R$	Input rise time	—	40	ns
$t_F$	Input fall time	—	40	ns
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	$\mu$ s
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	$4 \times$ maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$ <sup>(4)</sup>	—	—

**Notes to Table 51:**

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.
- (5) N is the DCLK-to-DATA ratio and  $f_{DCLK}$  is the DCLK frequency the system is operating.
- (6) If nSTATUS is monitored, follow the  $t_{ST2CK}$  specification. If nSTATUS is not monitored, follow the  $t_{CF2CK}$  specification.

**Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	μs
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$	—	—

**Notes to Table 53:**

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (2)  $t_{CF2CD}$ ,  $t_{CF2ST0}$ ,  $t_{CFG}$ ,  $t_{STATUS}$ , and  $t_{CF2ST1}$  timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

## Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

**Figure 15. PS Configuration Timing Waveform <sup>(1)</sup>****Notes to Figure 15:**

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF\_DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

